

### Final Product/Process Change Notification

Document # : FPCN22198X Issue Date: 8 March 2018

Title of Change:	Additional Assembly and Test Manufacturing Site at GE	Additional Assembly and Test Manufacturing Site at GEM Shanghai for Mosfet Devices Packaged in DPAK.		
Proposed first ship date:	15 June 2018			
Contact information:	Contact your local ON Semiconductor Sales Office or M	onsemi.com // Johd Hezri < MohdHezri.AbuBakar@onsemi.com		
Samples:	Contact your local ON Semiconductor Sales Office			
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or C	Contact your local ON Semiconductor Sales Office or Chean Ching Sim <ffxg4t@onsemi.com></ffxg4t@onsemi.com>		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.  ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>			
Change Part Identification:	Affected parts will be identified with a date code of WW24'18 or later.			
Change category:	☐ Wafer Fab Change ☐ Assembly Change	☐ Other		
Change Sub-Category(s):   ☐ Manufacturing Site Change/Addition ☐ Material Change ☐ Product specific change		☐ Datasheet/Product Doc change ☐ Shipping/Packaging/Marking ☐ Other:		
Sites Affected:	ON Semiconductor Sites: ON Dong Nai Province, Vietnam	External Foundry/Subcon Sites: GEM Electronics, Shanghai		

### **Description and Purpose:**

This FPCN announces the capacity expansion of ON Semiconductor's assembly and test operations of DPAK discrete packaged products, currently built at ON Semiconductor Vietnam (OSV) to GEM Shanghai.

Upon the expiration of this FPCN, Mosfet devices may be processed at either location. These products have been qualified to commodity/commercial requirements. These products will continue being Pb-free, Halide free and RoHS compliant.

	Before Change Description	After Change Description
Assembly/Test Site	OSV	OSV and GEM

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### **Reliability Data Summary:**

**QV DEVICE NAME: NTD6414ANT4G** 

RMS: V44641

PACKAGE: DPAK case 369AA

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=175°C, 80% max rated V	504 hrs	0/84
HTGB	JESD22-A108	Ta=175°C, 100% max rated Vgss	504 hrs	0/84
HTSL	JESD22-A103	Ta= 175°C	504 hrs	0/84
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	7500 cyc	0/84
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/84
H3TRB	JESD22-A101	Ta= 85°C, RH=85%, 80% bias	504 hrs	0/84
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/84
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		
RSH	JESD22- B106	Ta = 265C, 10 sec		0/30
SD	JSTD002	Ta = 245C, 10 sec		0/15

QV DEVICE NAME: NTD24N06LT4G

RMS: V44642

PACKAGE: DPAK case 369C

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=175°C, 80% max rated V	504 hrs	0/84
HTGB	JESD22-A108	Ta=175°C, 100% max rated Vgss	504 hrs	0/84
HTSL	JESD22-A103	Ta= 175°C	504 hrs	0/84
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	7500 cyc	0/84
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/84
H3TRB	JESD22-A101	Ta= 85°C, RH=85%, 80% bias	504 hrs	0/84
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/84
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		
RSH	JESD22- B106	Ta = 265C, 10 sec		0/30
SD	JSTD002	Ta = 245C, 10 sec		0/15

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**QV DEVICE NAME: NTD5802NT4G** 

RMS: V44643

PACKAGE: DPAK case 369C

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=175°C, 80% max rated V	504 hrs	0/84
HTGB	JESD22-A108	Ta=175°C, 100% max rated Vgss	504 hrs	0/84
HTSL	JESD22-A103	Ta= 175°C	504 hrs	0/84
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	7500 cyc	0/84
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/84
H3TRB	JESD22-A101	Ta= 85°C, RH=85%, 80% bias	504 hrs	0/84
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/84
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		
RSH	JESD22- B106	Ta = 265C, 10 sec		0/30
SD	JSTD002	Ta = 245C, 10 sec		0/15

### **Electrical Characteristic Summary:**

Electrical characteristic are not impacted.

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#### **List of Affected Standard Parts:**

Part Number	Qualification Vehicle
NTD2955T4G	
NTD20P06LT4G	
NTD3055L104T4G	
NTD3055-150T4G	
NTD3055-094T4G	
NTD20N06T4G	NTD24N06T4G
NTD18N06LT4G	
NTD24N06LT4G	
NTD3055L170T4G	
NTD20N06LT4G	
NTD24N06T4G	
NTD4858NT4G	
NTD4804NT4G	
NTD5802NT4G	
NTD4805NT4G	NTD5802NT4G
NTD4860NT4G	
NTD4809NT4G	
NTD4813NHT4G	
NTD25P03LT4G	
NTD6415ANLT4G	
NTD6416ANT4G	
NTD6416ANLT4G	NTDC 41 44 NT 4C
NTD14N03RT4G	NTD6414ANT4G
NTD20N03L27T4G	
NTD4302T4G	
NTD6414ANT4G	

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### **Appendix A: Changed Products**

Product	Customer Part Number	Qualification Vehicle	
NTD14N03RT4G		NTD6414ANT4G	
NTD18N06LT4G		NTD24N06T4G	
NTD20N03L27T4G		NTD6414ANT4G	
NTD20N06LT4G		NTD24N06T4G	
NTD20N06T4G		NTD24N06T4G	
NTD20P06LT4G		NTD24N06T4G	
NTD24N06LT4G		NTD24N06T4G	
NTD24N06T4G		NTD24N06T4G	
NTD25P03LT4G		NTD6414ANT4G	
NTD2955T4G		NTD24N06T4G	
NTD3055-094T4G		NTD24N06T4G	
NTD3055-150T4G		NTD24N06T4G	
NTD3055L104T4G		NTD24N06T4G	
NTD3055L170T4G		NTD24N06T4G	
NTD4302T4G		NTD6414ANT4G	
NTD4804NT4G		NTD5802NT4G	
NTD4805NT4G		NTD5802NT4G	
NTD4809NT4G		NTD5802NT4G	
NTD4813NHT4G		NTD5802NT4G	
NTD4858NT4G		NTD5802NT4G	
NTD4860NT4G		NTD5802NT4G	
NTD5802NT4G		NTD5802NT4G	
NTD6414ANT4G		NTD6414ANT4G	
NTD6415ANLT4G		NTD6414ANT4G	
NTD6416ANLT4G		NTD6414ANT4G	
NTD6416ANT4G		NTD6414ANT4G	